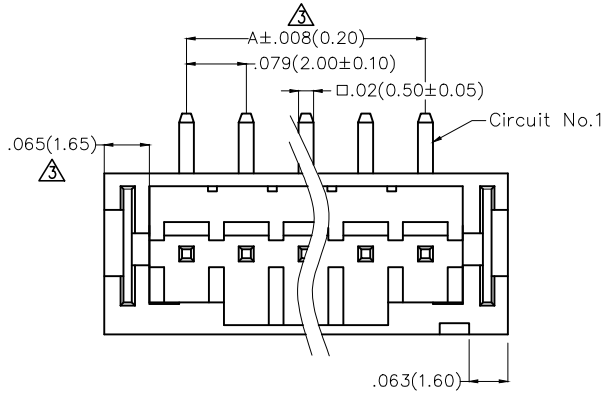


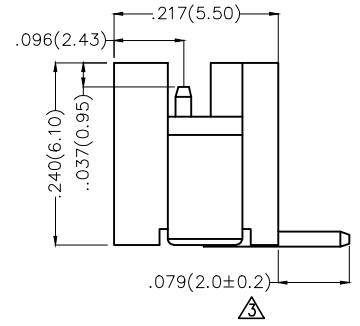
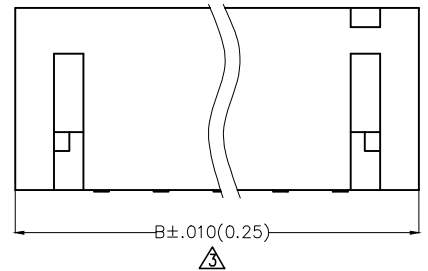
1 2 3 4 5 6 7 8

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△	MPQ 1500Pcs/Reel Change to 1000Pcs/Reel	20150921	CHERRY	FAN
2	△	Change the packing specification	05/MAY/17	KATE	FRANK
3	△	Size changes	24/JUN/21	KATE	FRANK



Electrical

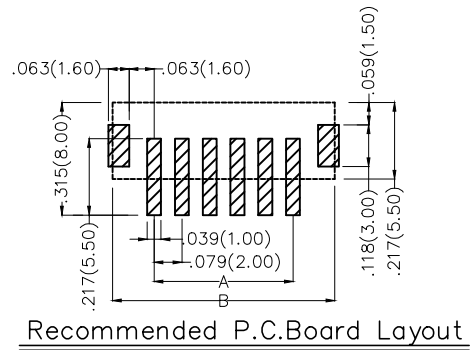
Current Rating: 2.0A AC(rms)/DC
 Voltage Rating: 100V AC(rms)/DC
 Contact Resistance: 10 mΩ Max
 Insulation Resistance: 1000 MΩ MIN
 Withstanding Voltage: 800V AC r.m.s
 Temperature Range-Operating: -25°C~+85°C
 Material and Plating
 Housing: PA9T(UL 94V-0)
 Contacts: Brass/ Tin Plated
 Solder tab: Phosphor bronze/ Tin Plated



Ordering Information

FWF 200 03 — S XX S 2 4 W5 M
 1 2 3 4 5 6 7 8 9 10

1	Category FWF-Wafer	2	Series Number 200-Pitch2.0mm	3	Distinction No. 03	4	Row Option S-Single Row	5	Circuits XX	6	Entry Angle S-180° Vertical
7	Plating 2-Tin Plated	8	Material-Resin 4-PA9T	9	Color-Resin W5-White	10	Packaging M-Reel				



 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 18/JUN/13	PART NO. FWF20003-SXXS24W5M	ITEM NO. FWF20003	 Leader Of Industry	
	X.±.012(0.30)	X'±5'	CHECKED BY JACOB	DATE 18/JUN/13	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (SMT)			REV 3
DESIGN UNITS Inch (metric)	X.XX±.008(0.20)	.X'±2'	DRAWN BY CHERRY	DATE 18/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
SCALE 5:1	SIZE A4	X.XXX±.004(0.10)	.XX'±0.5'					

1 2 3 4 5 6 7 8

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

A

B

C

D

E

F

A

B

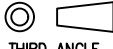

C

D

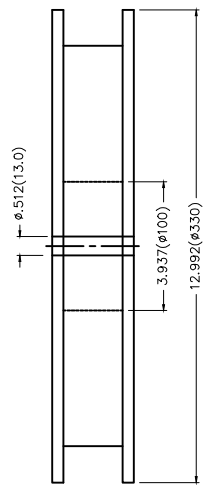
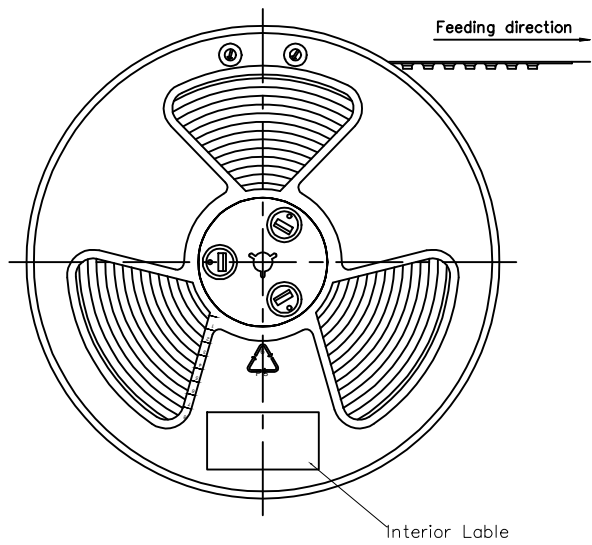
E

F

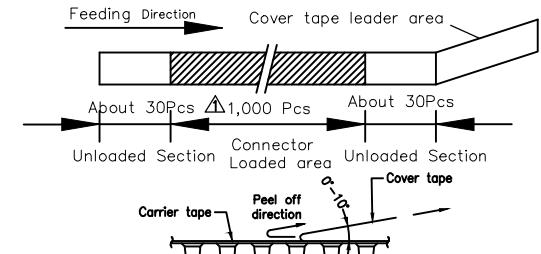
Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B
2	FWF20003-S02S24W5M	.079(2.00)	.315(8.00)
3	FWF20003-S03S24W5M	.157(4.00)	.394(10.00)
4	FWF20003-S04S24W5M	.236(6.00)	.472(12.00)
5	FWF20003-S05S24W5M	.315(8.00)	.551(14.00)
6	FWF20003-S06S24W5M	.394(10.00)	.630(16.00)
7	FWF20003-S07S24W5M	.472(12.00)	.709(18.00)
8	FWF20003-S08S24W5M	.551(14.00)	.787(20.00)
9	FWF20003-S09S24W5M	.630(16.00)	.866(22.00)
10	FWF20003-S10S24W5M	.709(18.00)	.945(24.00)
11	FWF20003-S11S24W5M	.787(20.00)	1.024(26.00)
12	FWF20003-S12S24W5M	.866(22.00)	1.102(28.00)
13	FWF20003-S13S24W5M	.945(24.00)	1.181(30.00)
14	FWF20003-S14S24W5M	1.024(26.00)	1.260(32.00)
15	FWF20003-S15S24W5M	1.102(28.00)	1.339(34.00)

 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 18/JUN/13	PART NO. FWF20003-SXXS24W5M	ITEM NO. FWF20003	 Leader Of Industry	
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.±5'	CHECKED BY JACOB	DATE 18/JUN/13	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (SMT)			REV 3 SHEET NO. 2/3
	SCALE 5:1	SIZE A4	X.XX±.008(0.20) .X'±2' X.XX±.006(0.15) .XX'±1' X.XXX±.004(0.10) .XXX'±0.5'	DRAWN BY CHERRY	DATE 18/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

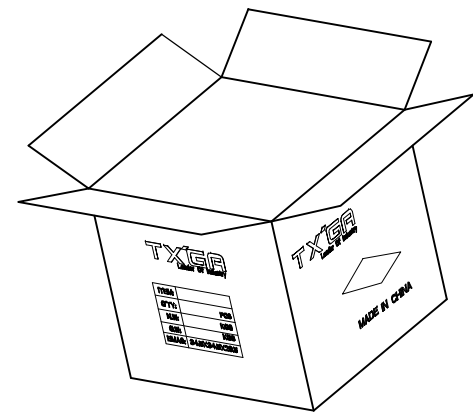
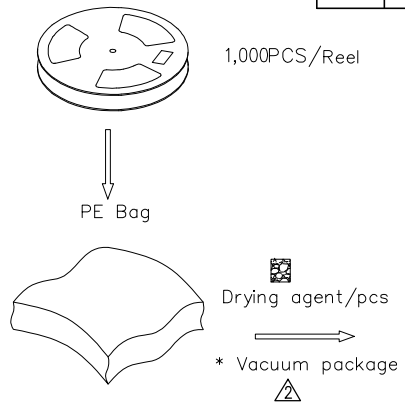
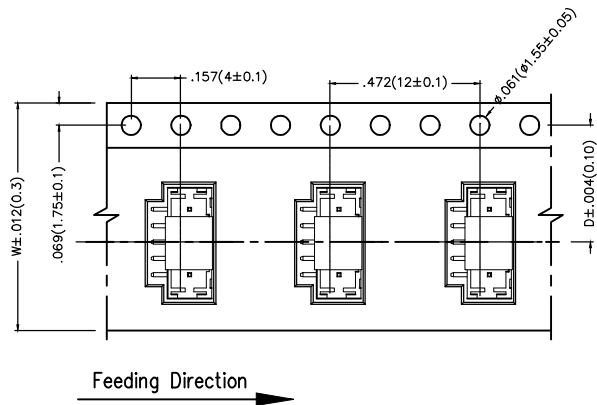
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



- Note:**
- 10 sprocket hole cumulative tolerance ± 0.2
 - Carrier camber is within 1.0mm in 100mm
 - Material: White Conductive polystyrene Alloy 100% recyclable
 - All dimensions meet EIA-481-3 requirements
 - Component load per 13" reel: 1,000pcs



Circuits (n)	Dimensions(in/mm)		Circuits (n)	Dimensions(in/mm)	
	D	W		D	W
2	.295(7.50)	.630(16.00)	9	.559(14.20)	1.260(32.00)
3	.295(7.50)	.630(16.00)	10	.559(14.20)	1.260(32.00)
4	.453(11.50)	.945(24.00)	11	.795(20.20)	1.732(44.00)
5	.453(11.50)	.945(24.00)	12	.795(20.20)	1.732(44.00)
6	.453(11.50)	.945(24.00)	13	.795(20.20)	1.732(44.00)
7	.559(14.20)	1.260(32.00)	14	.795(20.20)	1.732(44.00)
8	.559(14.20)	1.260(32.00)	15	.795(20.20)	1.732(44.00)



 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	 Leader Of Industry	
	X.±.012(0.30)	X.±5'	FRANK	18/JUN/13	FWF20003-SXXS24W5M	FWF20003		
	DESIGN UNITS Inch (metric)	X.X±.008(0.20)	.X'±2'	CHECKED BY	DATE	TITLE		REV 3
	SCALE 5:1	X.XX±.006(0.15)	.XX'±1'	JACOB	18/JUN/13	Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (SMT)		SHEET NO. 3/3
	X.XXX±.004(0.10)	.XXX'±0.5'	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
			CHERRY	18/JUN/13				